

## NCE N-Channel Enhancement Mode Power MOSFET

### **Description**

The NCE3025Q uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. It can be used in a wide variety of applications.

### **General Features**

V<sub>DS</sub> =30V,I<sub>D</sub> =25A

 $R_{DS(ON)}$  < 10m $\Omega$  @  $V_{GS}$ =10V

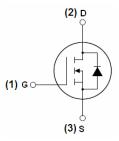
 $R_{DS(ON)}$  < 14m $\Omega$  @  $V_{GS}$ =4.5V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

### **Application**

- SMPS and general purpose applications
- Hard switched and high frequency circuits
- Uninterruptible power supply

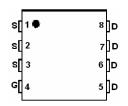
100% UIS TESTED!



Schematic diagram



### Marking and pin Assignment



DFN 3x3 EP top view

### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE3025Q	NCE3025Q	DFN 3x3 EP	-	-	-

## Absolute Maximum Ratings (T<sub>C</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	±20	V	
Drain Current-Continuous	I <sub>D</sub>	25	Α	
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	17	Α	
Pulsed Drain Current	I <sub>DM</sub>	50	А	
Maximum Power Dissipation	P <sub>D</sub>	25	W	
Derating factor		0.2	W/℃	
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	70	mJ	
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$ C	

NCE3025Q

## **Thermal Characteristic**

Thermal Resistance, Junction-to-Case (Note 2)	$R_{ heta JC}$	5	°C/W	
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# Electrical Characteristics (T<sub>C</sub>=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics	·						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	BV <sub>DSS</sub> V <sub>GS</sub> =0V I <sub>D</sub> =250μA		33	-	V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	-	-	1	μA	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA	
On Characteristics (Note 3)	·						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	1	1.6	3	V	
Drain-Source On-State Resistance	В	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	-	7.0	10		
Diain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A -		10.5	14	mΩ	
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =20A	15	-	-	S	
Dynamic Characteristics (Note4)			•				
Input Capacitance	C <sub>lss</sub>	\/ -45\/\/ -0\/	-	1530	-	PF	
Output Capacitance	Coss	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V, F=1.0MHz	-	250	-	PF	
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.UIVID2	-	198	-	PF	
Switching Characteristics (Note 4)	·						
Turn-on Delay Time	t <sub>d(on)</sub>		-	10	-	nS	
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =15V,I <sub>D</sub> =10A	-	8	-	nS	
Turn-Off Delay Time	$t_{d(off)}$ $V_{GS}$ =10V, $R_{GEN}$ =1.8 $\Omega$		-	30	-	nS	
Turn-Off Fall Time	t <sub>f</sub>		-	5	-	nS	
Total Gate Charge	Qg	\/ -15\/   -0.0	-	15	-	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =15V, $I_{D}$ =9A, $V_{GS}$ =10V	-	3	-	nC	
Gate-Drain Charge	$Q_{gd}$	V GS-10 V	-	4.5	-	nC	
Drain-Source Diode Characteristics	·						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =10A	-	0.85	1.2	V	
Diode Forward Current (Note 2)	Is		-	-	25	Α	
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, IF = 10A	-	22	35	nS	
Reverse Recovery Charge	Qrr	di/dt = 100A/µs(Note3)		12	20	nC	
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LI					

### Notes:

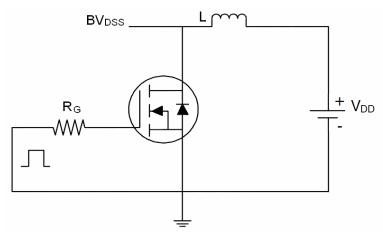
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- **4.** Guaranteed by design, not subject to production
- 5. EAS condition: Tj=25  $^{\circ}$ C,VDD=15V,VG=10V,L=0.1mH,Rg=25 $\Omega$



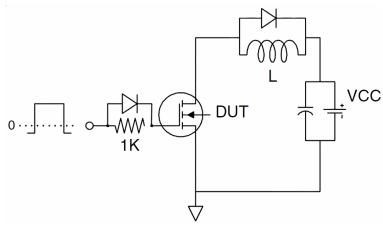
# NCE3025Q

# **Test Circuit**

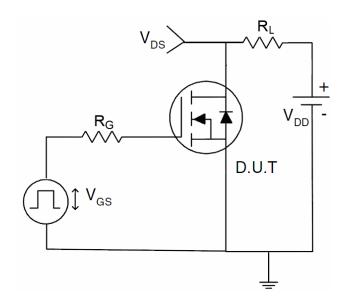
# 1) E<sub>AS</sub> Test Circuit



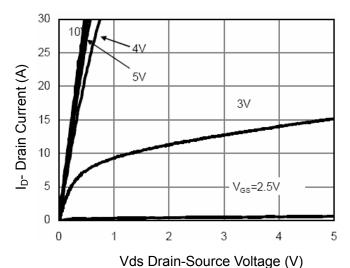
# 2) Gate Charge Test Circuit



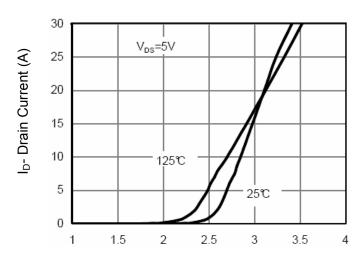
# 3) Switch Time Test Circuit



# **Typical Electrical and Thermal Characteristics (Curves)**



**Figure 1 Output Characteristics** 



Vgs Gate-Source Voltage (V) **Figure 2 Transfer Characteristics** 

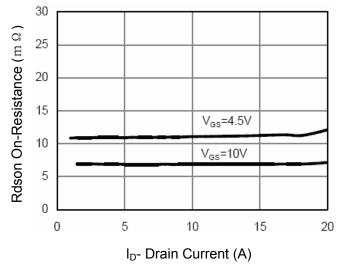
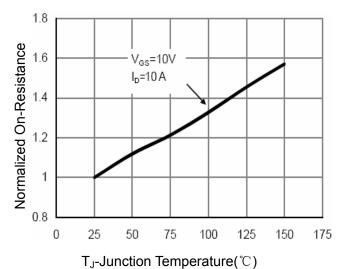


Figure 3 Rdson- Drain Current



**Figure 4 Rdson-Junction Temperature** 

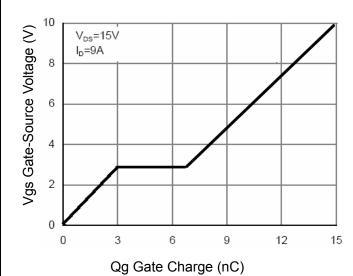


Figure 5 Gate Charge

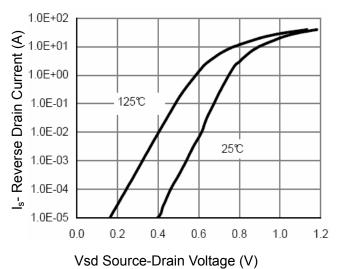


Figure 6 Source- Drain Diode Forward



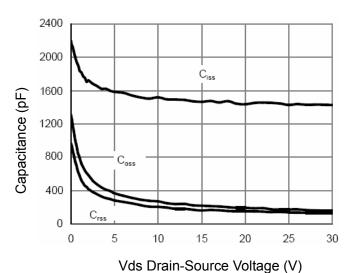


Figure 7 Capacitance vs Vds

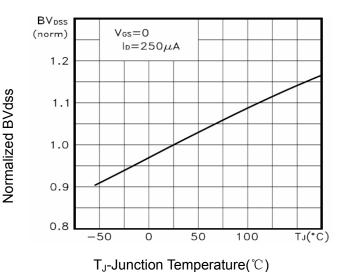


Figure 9 BV<sub>DSS</sub> vs Junction Temperature

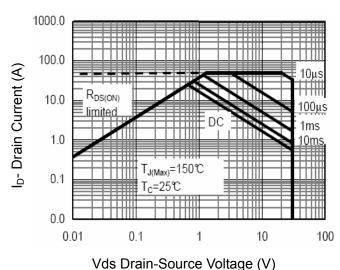
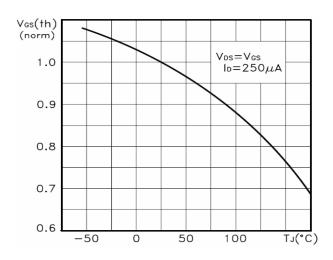
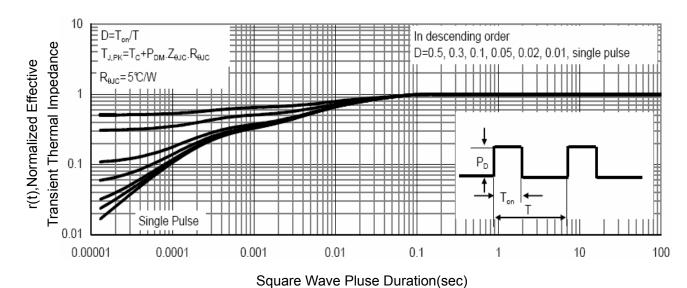


Figure 8 Safe Operation Area

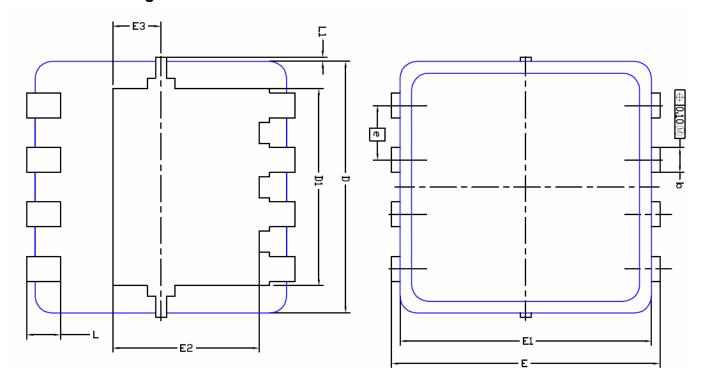


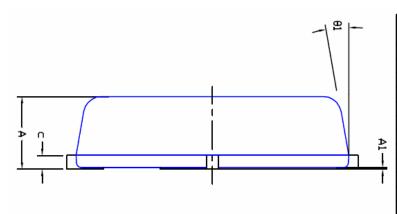


**Figure 11 Normalized Maximum Transient Thermal Impedance** 



# **DFN3X3 EP Package Information**





DIM.	MILLIMETERS			INCHES			
יואדת	MIN	NDM	MAX	MIN	NDM	MAX	
Α	0.700	0.80	0.900	0.0276	0.0315 0.035		
A1	0.00	i	0.05	0.000	0.002		
q	0,24	0'30	0,35	0,009	0.012	0.014	
U	0,10	0,152	0,25	0,004	0,006	0,010	
D	3.00 BSC			0.118 BSC			
D1	2.35 BSC			0.093 BSC			
Ε	O	3.20 BS	BSC 0.126 BSC			ő	
E1	3.00 B2C			0.118 BSC			
E2	1.75 BSC			0.069 BSC			
E3	0.575 BSC			0.023 B2C			
е	0	0.65 BSC 0.026 BS0			2		
L	0.30	0.40	0,50	0.0118	0.0157	0.0197	
L1	0		0.100	0		0.004	
θ1	0°	10°	12°	0°	10°	12*	

### http://www.ncepower.com

**NCE3025Q** 

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